# PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2

# EPAS ID: PAT2759185

SUBMISSION TYPE:			NEW ASSIGNMENT			
NATURE OF CONVEYANCE:			ASSIGNMENT			
CONVEYING PARTY DATA						
N			lame Execution Date			
ZVI OR-BACH				03/07/2014		
ZEEV WURMAN				03/07/2014		
RECEIVING PARTY DATA						
Name:	MonolithIC 3D Inc	MonolithIC 3D Inc.				
Street Address:	3555 Woodford D	3555 Woodford Drive				
City:	San Jose	San Jose				
State/Country:	CALIFORNIA	CALIFORNIA				
Postal Code:	95124	95124				
PROPERTY NUMBERS Total: 1 Property Type Number						
		2000	0061			
CORRESPONDENCE DATA Fax Number: Email: Brian@MonolithIC3D.com						
Correspondence will be sent via US Mail when the email attempt is unsuccessful.						
Correspondent Name: BRIAN CRONQUIST						
Address Line 1:       3555 WOODFORD DRIVE         Address Line 4:       SAN JOSE, CALIFORNIA 95124						
ATTORNEY DOCKET NUMBER:			MONOLITHIC3D-ZW8CON2			
NAME OF SUBMITTER:			BRIAN CRONQUIST			
Signature:			/bc/			
Date:			03/07/2014			
Total Attachments: 2 source=MonolithIC3D-ZW8con2_Assignment_Zvi_s#page1.tif source=MonolithIC3D-ZW8con2_Assignment_Zeev_s#page1.tif						

MonolithIC3D-ZW8con2

#### **ASSIGNMENT**

Whereas, I, Zvi Or-Bach (hereinafter referred to as Assignor(s)), residing in San Jose, California; have made a certain invention, and executed United States Patent Application entitled:

### Fabrication of Semiconductor Devices

as described in U.S. Patent Application Serial No. 14/200,061 and filed on March 07, 2014; and

Whereas, MonolithIC 3D<sup>™</sup> Inc., a company located at 3555 Woodford Drive, San Jose, California 95124 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

**INVENTOR:** DATE on 3-7- 2014 (Zvi **Or-Bach**) First Name Middle Initial Last Name

#### **ASSIGNMENT**

Whereas, I, Ze'ev Wurman (hereinafter referred to as Assignor(s)), residing in San Jose, California; have made a certain invention, and executed United States Patent Application entitled:

## Fabrication of Semiconductor Devices

as described in U.S. Patent Application Serial No. 14/200,061 and filed on March 07, 2014; and

Whereas, MonolithIC 3D<sup>™</sup> Inc., a company located at 3555 Woodford Drive, San Jose, California 95124 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

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Signed and Sealed:

#### **INVENTOR:**

DATE on 3/7/14

(Ze'ev	
First Nam	e

Middle Initial

Wurman) Last Name

PATENT REEL: 032383 FRAME: 0719

**RECORDED: 03/07/2014**